



FOR IMMEDIATE RELEASE

HDP User Group Announces i3 Electronics as New Member

Cave Creek, Arizona June 3, 2015. The High Density Packaging (HDP) User Group headquartered in the United States is pleased to announce that i3 Electronics, Inc. has become a member.

“We are very interested in collaborating with other member companies and providing enabling high performance interconnect solutions to several of the HDP programs.” said Frank Egitto, Director of Research and Development for i3.

“i3 Electronics is the newest member of HDP User Group. i3 has a long history of delivering advanced technologies to the industry. We welcome their participation in our Mini-Power Cycle project which is studying the reliability impact of frequent off-and-on operation seen in many electronics products today”, said Marshall Andrews, Executive Director of HDP User Group.

As a Member, i3 Electronics will join over 50 of the major companies involved in the design and manufacturing of electronic products worldwide in addressing the major technical and environmental issues facing the industry today. Their participation will complement the other member companies and help keep HDP User Group technical projects moving forward.

About i3 Electronics, Inc.

i3 Electronics, Inc. is a world leader in high-performance printed circuit board fabrication & assembly, semiconductor packaging, systems integration & test, advanced laboratory services and contract R&D. Our technology can be found in the world's fastest supercomputers, life-saving medical devices, complex imaging systems, mission-critical defense applications and thousands of other products, throughout the world.

For more information, visit i3 Electronics on the internet at www.i3electronics.com or contact Neal Driver, Director of Business Development at (607) 755-1985

About HDP User Group

HDP User Group (www.hdpug.org) is a global research and development organization based in Cave Creek Arizona, is dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas; and Stockholm, Sweden.



Technology Development in Today's Global Environment

www.hdpug.org

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963